

MA2J116 (MA116)

Silicon epitaxial planar type

For general purpose

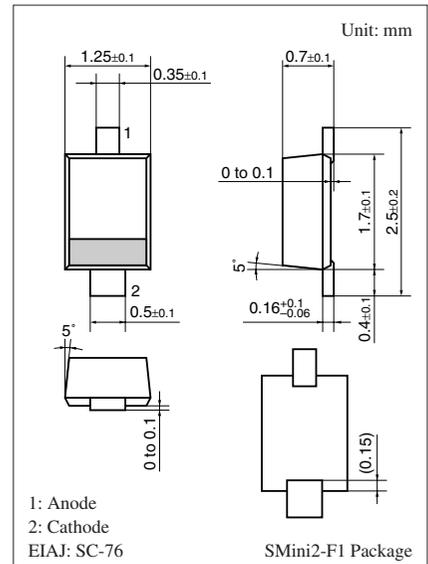
■ Features

- Allowing high-density mounting
- Soft recovery characteristic: $t_{rr} = 100$ ns

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

| Parameter | Symbol | Rating | Unit |
|---|-------------|-------------|------------------|
| Reverse voltage | V_R | 40 | V |
| Maximum peak reverse voltage | V_{RM} | 40 | V |
| Forward current (Average) | $I_{F(AV)}$ | 100 | mA |
| Peak forward current | I_{FM} | 225 | mA |
| Non-repetitive peak forward surge current * | I_{FSM} | 500 | mA |
| Junction temperature | T_j | 150 | $^\circ\text{C}$ |
| Storage temperature | T_{stg} | -55 to +150 | $^\circ\text{C}$ |

Note) *: $t = 1$ s



Marking Symbol: 1H

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

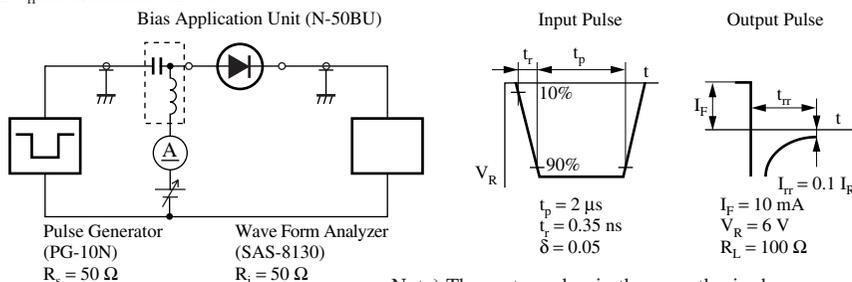
| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|-------------------------------|----------|---|-----|-----|-----|---------------|
| Forward voltage | V_F | $I_F = 100$ mA | | | 1.2 | V |
| Reverse voltage | V_R | $I_R = 100$ μA | 35 | | | V |
| Reverse current | I_{R1} | $V_R = 15$ V | | | 5 | nA |
| | | $V_R = 40$ V | | | 10 | |
| | | $V_R = 35$ V, $T_a = 100^\circ\text{C}$ | | | 100 | μA |
| Terminal capacitance | C_t | $V_R = 6$ V, $f = 1$ MHz | | 1.0 | 2.0 | pF |
| Forward dynamic resistance *1 | r_f | $I_F = 3$ mA, $f = 30$ MHz | | | 3.6 | Ω |
| Reverse recovery time *2 | t_{rr} | $I_F = 10$ mA, $V_R = 6$ V $I_{Tr} = 0.1 I_R$, $R_L = 100$ Ω | | | 100 | ns |

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

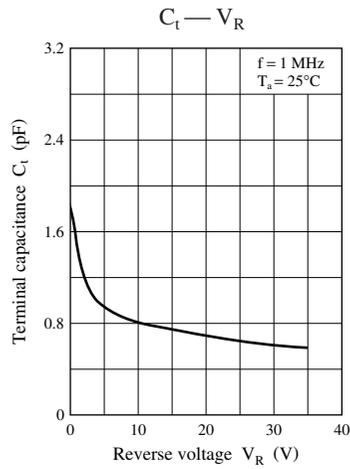
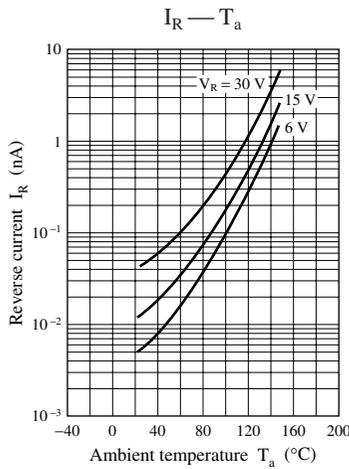
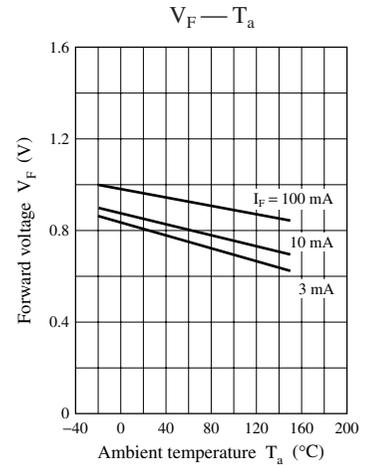
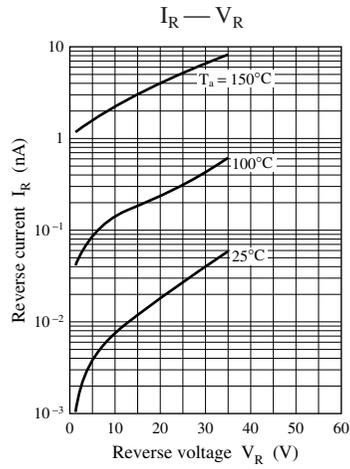
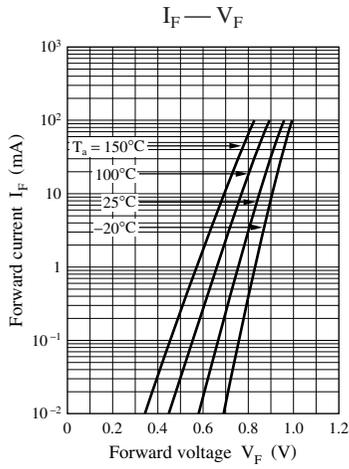
2. Absolute frequency of input and output is 10 MHz.

3. *1: YHP 4191A RF IMPEDANCE ANALYZER

*2: t_{rr} measurement circuit



Note) The part number in the parenthesis shows conventional part number.



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